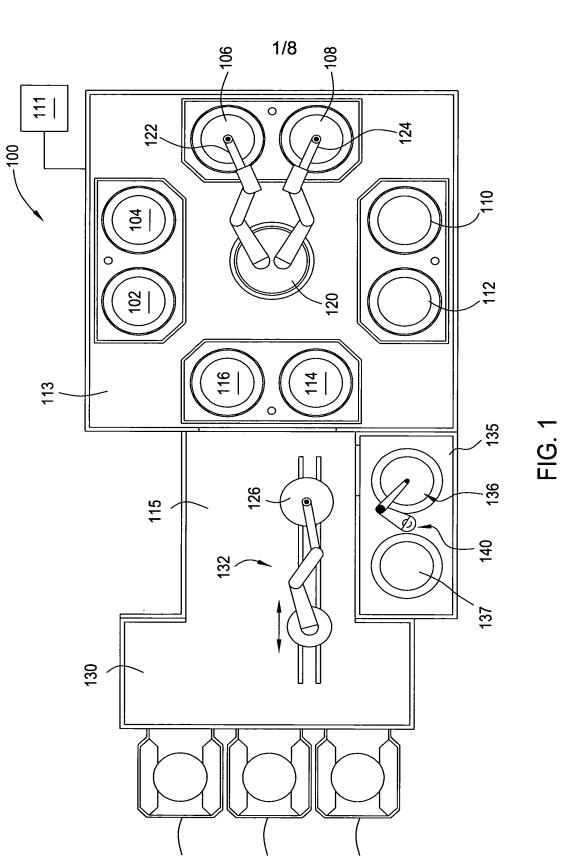
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TITLE: APPARATUS TO IMPROVE WAFER TEMPERATURE
JNIFORMITY FOR FACE-UP WET PROCESSING
INVENTOR: IAN A. PANCHAM, ET AL.
EXPRESS MAIL NO.: EV351032045US PAGE 1 OF 8

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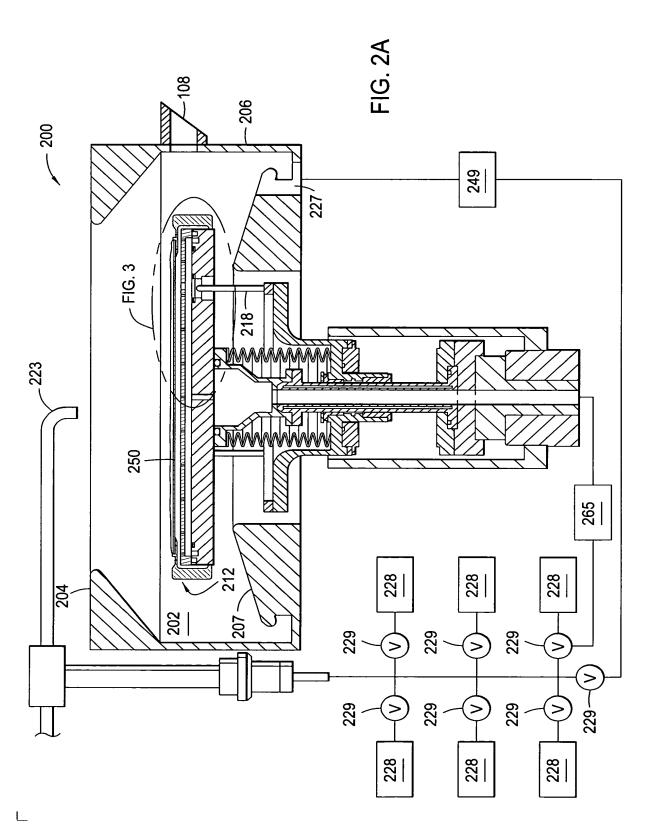
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TITLE: APPARATUS TO IMPROVE WAFER TEMPERATURE
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INVENTOR: IAN A. PANCHAM, ET AL.

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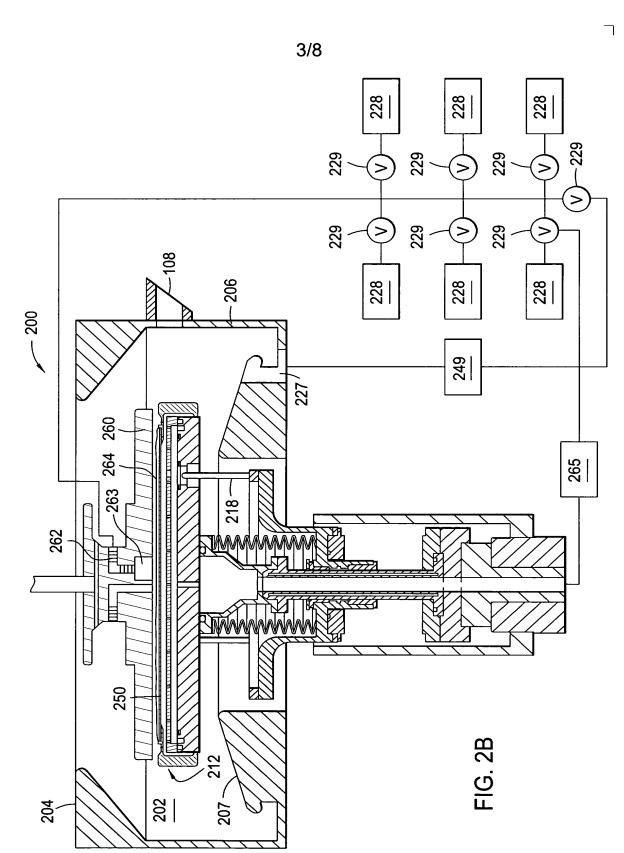
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INVENTOR: IAN A. PANCHAM, ET AL.
EXPRESS MAIL NO.: EV351032045US
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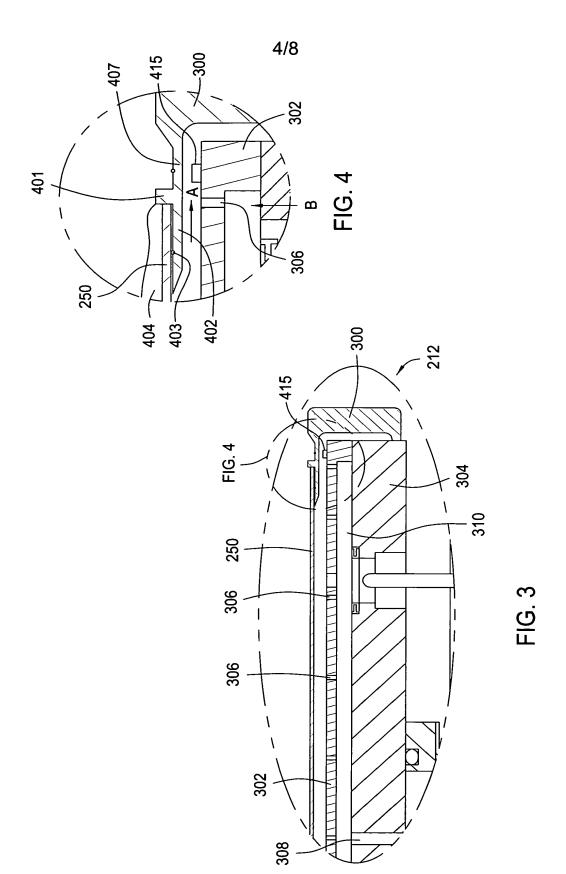


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APPLICANT: APPLIED MATERIALS
TITLE: APPARATUS TO IMPROVE WAFER TEMPERATURE
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INVENTOR: IAN A. PANCHAM, ET AL.
EXPRESS MAIL NO.: EV351032045US PAGE 4 OF 8



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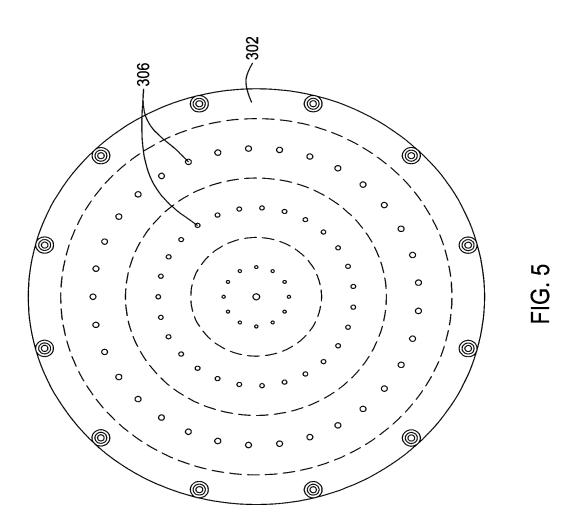
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TITLE: APPARATUS TO IMPROVE WAFER TEMPERATURE
JNIFORMITY FOR FACE-UP WET PROCESSING
INVENTOR: IAN A. PANCHAM, ET AL.

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INVENTOR: IAN A. PANCHAM, ET AL.
EXPRESS MAIL NO.: EV351032045 I.S.
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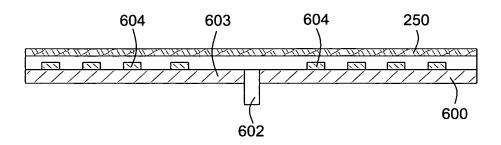


FIG. 6

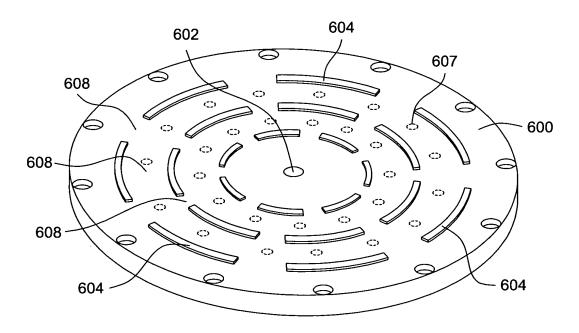


FIG. 7

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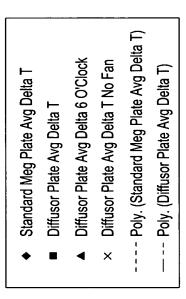
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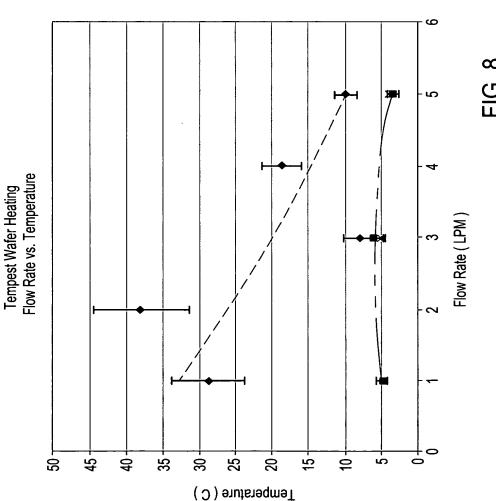
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JNIFORMITY FOR FACE-UP WET PROCESSING

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UNIFORMITY FOR FACE-UP WET PROCESSING
INVENTOR: IAN A. PANCHAM, ET AL.
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